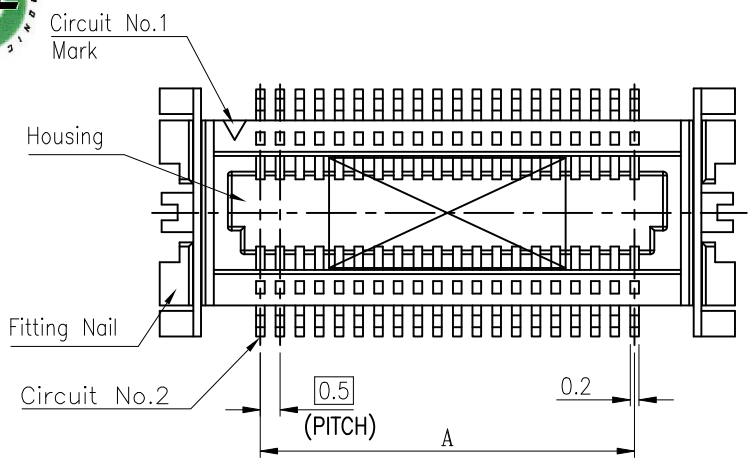
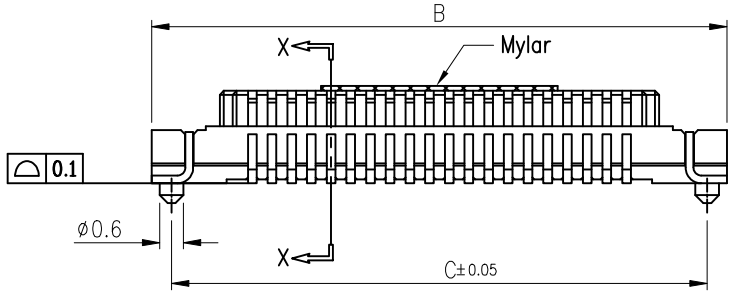
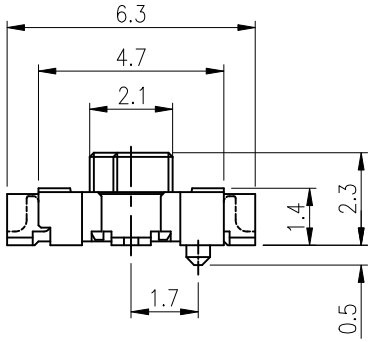






NOTES:
1. MATERIAL:
   1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
   1.2 CONTACT: PHOSPHOR BRONZE
   1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:50~100u" NICKEL UNDERPLATING OVERALL.
   1:1u"~3u" MIN GOLD FLASH PLATING OVERALL.
   N:100u"~200u" MATTE TIN OVERALL,
   T:10u" GOLD ON CONTACT OVERALL
   2.2 FITTING NAIL:50~100u" NICKEL UNDERPLATING OVERALL.
   N:100u"~200u" MATTE TIN OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50058-XXXXX-XXX
5. PACKAGE PLS. REFER TO 88068-XXXX-TRP
6. PART NUMBER

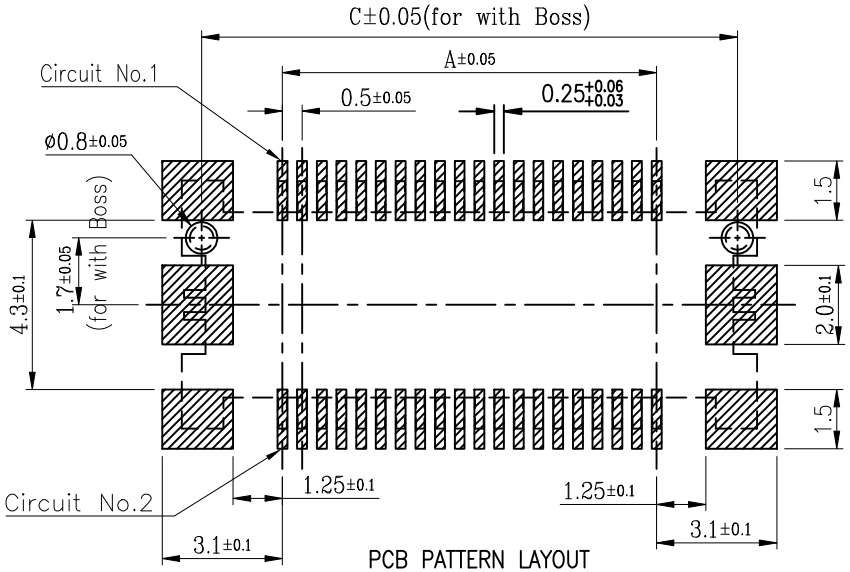
P/N LEGEND
50058-XXX X X-XXX

NO OF CKT

PACKING
1:TUBE PACKAGE
0:TAPE & REEL

PLATING
1:GOLD FLASH OVERALL
N:MATTE TIN(LEAD FREE)
T:10u" GOLD ON CONTACT OVERALL

XXX	Housing Color	Polarization	Halogen Free
001	Black	With Boss	HF
002	Black	Without Boss	HF



PCB PATTERN LAYOUT

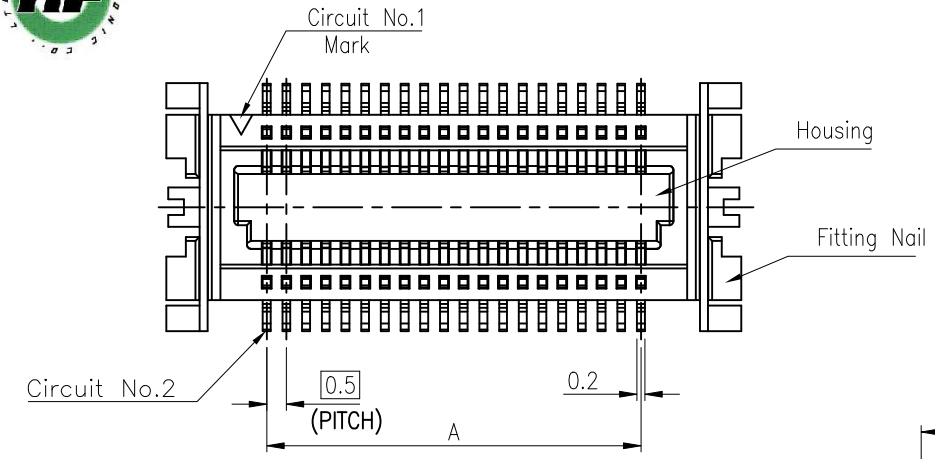
CKT	Dim A	Dim B	Dim C	CKT	Dim A	Dim B	Dim C
10	2.0	7.1	6.1	40			
14	3.0	8.1	7.1	44	10.5	15.6	14.6
16	3.5	8.6	7.6	50	12.0	17.1	16.1
20	4.5	9.6	8.6	60			
22	5.0	10.1	9.1	80	19.5	24.6	23.6
24	5.5	10.6	9.6	100	24.5	29.6	28.6
30	7.0	12.1	11.1	120	29.5	34.6	33.6
34	8.0	13.1	12.1	140	34.5	39.6	38.6
36	8.5	13.6	12.6				

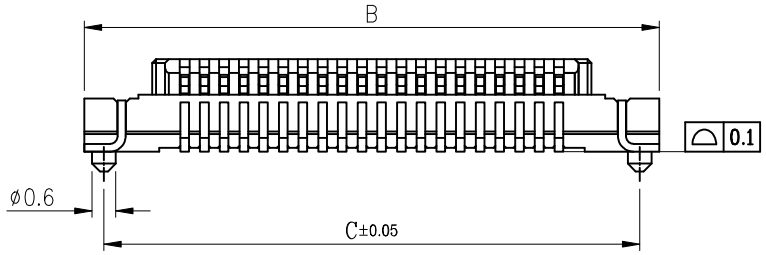
一般公差
TOLERANCES
X. ±0.5 .XX ±0.15
.X ±0.25 .XXX ±0.1
ANGLES ±2°

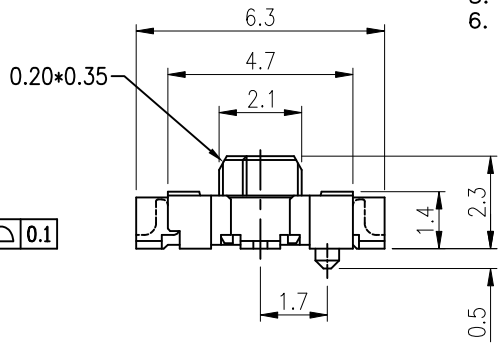
宏致電子股份有限公司
Aces Electronic Co.,Ltd.

檢驗尺寸標示
SYMBOLS (CR) (MA) INDICATE CLASSIFICATION DIMENSION
(CR) MARK IS CRITICAL DIM.
(MA) MARK IS MAJOR DIM.

品名 (TITLE): 0.5mm BTB D/R CONN. SMT S/T TYPE
圖號 (DWG.NO): 50058-XXXXX-XXX
製圖 (DR): 23/08/02 MengMeng
審核 (CHKD): BRAVE
核准 (APPD): BRAVE
表面處理 (FINISH):
比例 (SCALE): 5:1
單位 (UNITS): mm
張數 (SHEET): 1 OF 2
SIZE: A4
REV: E







NOTES:
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   T:10u" GOLD ON CONTACT OVERALL
   C:15u" Au on contact(Lead free)
   D:30u" GOLD ON CONTACT OVERALL
   2.2 FITTING NAIL:50~100u" NICKEL UNDERPLATING OVERALL.
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3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50058-XXXXX-XXX
5. PACKAGE PLS. REFER TO 88068-XXXX-TRP
6. PART NUMBER

P/N LEGEND
50058-XXX X X-XXX

NO OF CKT

PACKING
1:TUBE PACKAGE
0:TAPE & REEL

PLATING
1:GOLD FLASH OVERALL
N:MATTE TIN(LEAD FREE)
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XXX	Housing Color	Polarization	Halogen Free
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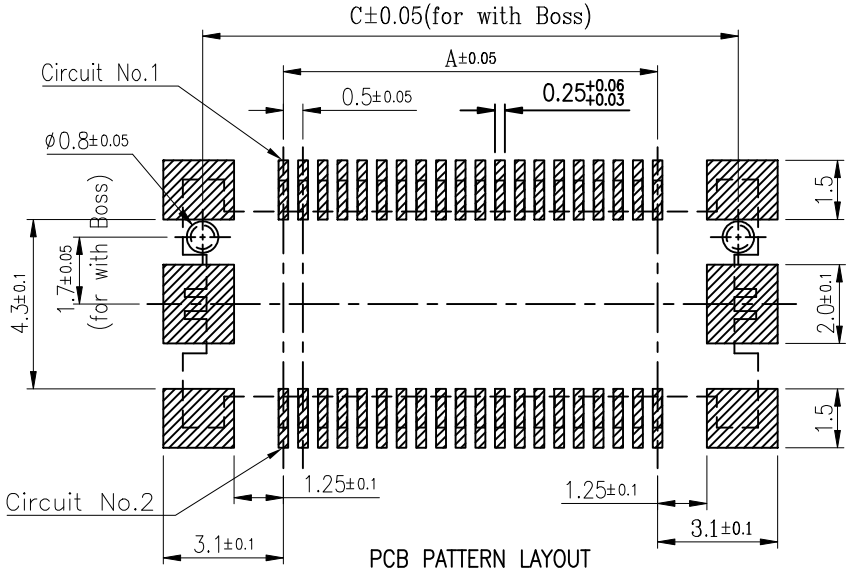

PCB PATTERN LAYOUT

CKT	Dim A	Dim B	Dim C	M/Size
40	9.5	14.6	13.6	6*2.8
60	14.5	19.6	18.6	

一般公差
TOLERANCES
X. ±0.5 .XX ±0.15
.X ±0.25 .XXX ±0.1
ANGLES ±2°

宏致電子股份有限公司
Aces Electronic Co.,Ltd.

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SYMBOLS (C) (M) INDICATE CLASSIFICATION DIMENSION
(C) MARK IS CRITICAL DIM.
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品名 (TITLE): 0.5mm BTB D/R CONN. SMT S/T TYPE

圖號 (DWG.NO): 50058-XXXXX-XXX

製圖 (DR): 23/08/02 MengMeng
審核 (CHKD): BRAVE
核准 (APPD): BRAVE

表面處理 (FINISH)
比例 (SCALE): 5:1
單位 (UNITS): mm
張數 (SHEET): 2 OF 2
SIZE: A4
REV: E